

Title (en)

DEVICE FOR BREAKING SEMICONDUCTOR WAFERS OR SIMILAR SUBSTRATES

Title (de)

VORRICHTUNG ZUM BRECHEN VON HALBLEITERSCHEIBEN ODER ÄHNLICHEN SUBSTRATEN

Title (fr)

DISPOSITIF POUR BRISER DES PLAQUETTES À SEMI-CONDUCTEURS OU DES SUBSTRATS SIMILAIRES

Publication

**EP 2004374 A1 20081224 (DE)**

Application

**EP 07723840 A 20070330**

Priority

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- DE 102006015142 A 20060331

Abstract (en)

[origin: DE102006015142A1] The device has a breaking wedge (4) arranged at a lower side of a semiconductor wafer (1) aligned to a preset break line. Two counter supports (5, 6) are provided and are turned towards a top side of the wafer, where the counter supports are positioned vertically and horizontally at sides of the preset break line, and the sides are arranged opposite to each other. The two counter supports are positionable independent of each other.

IPC 8 full level

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CPC (source: EP)

**B28D 5/0011** (2013.01); **B28D 5/0023** (2013.01); **B28D 5/0052** (2013.01); **C03B 33/033** (2013.01)

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DOCDB simple family (publication)

**DE 102006015142 A1 20071004**; **DE 102006015142 B4 20140220**; EP 2004374 A1 20081224; WO 2007112983 A1 20071011

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